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Vishay Siliconix

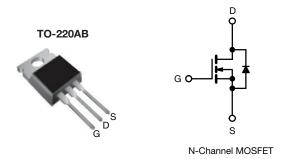
RoHS

COMPLIANT HALOGEN

FREE

EF Series Power MOSFET with Fast Body Diode

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V	0.123			
Q _g (Max.) (nC)	120				
Q _{gs} (nC)	17				
Q _{gd} (nC)	33				
Configuration	Single				



FEATURES

- Fast body diode MOSFET using E series technology
- Reduced t_{rr}, Q_{rr}, and I_{RRM}
- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Low switching losses due to reduced Q_{rr}
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- Lighting
 - High intensity discharge (HID)
 - Light emitting diodes (LEDs)
- Consumer and computing
 - ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- · Renewable energy
 - Solar (PV inverters)
- Switch mode power suppliers (SMPS)
- Applications using the following topologies
 - LLC
 - Phase shifted bridge (ZVS)
 - 3-level inverter
 - AC/DC bridge

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and Halogen-free	SiHP28N60EF-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	600	V	
Gate-Source Voltage			V_{GS}	± 30]	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C		28	A	
		T _C = 100 °C		18		
Pulsed Drain Current ^a			I _{DM}	75		
Linear Derating Factor				2	W/°C	
Single Pulse Avalanche Energy b			E _{AS}	691	mJ	
Maximum Power Dissipation			P _D	250	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C		
Drain-Source Voltage Slope	T _J = 125 °C		70		1//20	
Reverse Diode dV/dt ^d			dV/dt	50	V/ns	
Soldering Recommendations (Peak Temperature) c	for 10 s			300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 7 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 900 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.5	C/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static				L			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	600	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	-	0.76	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Coto Courso Lookago		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V		-	± 1	μΑ
Zava Cata Valtaga Drain Current		V _{DS} =	V _{DS} = 480 V, V _{GS} = 0 V	-	-	1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 V	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	2	mA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 14 A	-	0.107	0.123	Ω
Forward Transconductance	9 _{fs}	$V_{DS} = 30 \text{ V}, I_D = 14 \text{ A}$		-	9.7	-	S
Dynamic							
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 1 \text{ MHz}$		-	2714	-	
Output Capacitance	C _{oss}			-	123	-	1
Reverse Transfer Capacitance	C _{rss}			-	6	-	pF
Effective output capacitance, energy related ^a	C _{o(er)}	V _{GS} = 0 V, V _{DS} = 0 V to 480 V		-	98	-	
Effective output capacitance, time related b	C _{o(tr)}			-	356	-	
Total Gate Charge	Qg			-	80	120	
Gate-Source Charge	Q_{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 14 \text{ A}, V_{DS} = 480 \text{ V}$		-	17	-	nC
Gate-Drain Charge	Q _{gd}			-	33	-	1
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 480 \text{ V}, I_{D} = 14 \text{ A}$ $R_{g} = 9.1 \Omega, V_{GS} = 10 \text{ V}$		-	24	48	- ns
Rise Time	t _r			-	40	80	
Turn-Off Delay Time	t _{d(off)}			-	82	123	
Fall Time	t _f			-	39	78	
Gate Input Resistance	R_g	f = 1 MHz, open drain		0.2	0.5	1.0	Ω
Drain-Source Body Diode Characteristics	1						
Continuous Source-Drain Diode Current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	28	
Pulsed Diode Forward Current	I _{SM}			-	-	70	- A
Diode Forward Voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 11 \text{A}, V_{GS} = 0 \text{V}$		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = I _S = 14 A, dl/dt = 100 A/µs, V _R = 400 V		-	142	284	ns
Reverse Recovery Charge	Q _{rr}			-	0.97	1.94	μC
Reverse Recovery Current	I _{RRM}			-	13.2	_	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

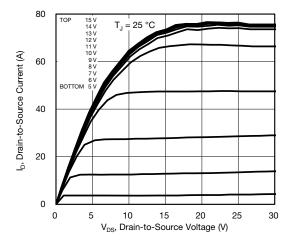


Fig. 1 - Typical Output Characteristics

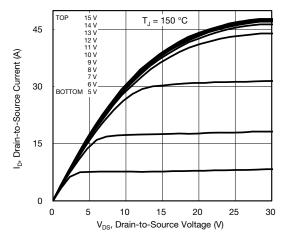


Fig. 2 - Typical Output Characteristics

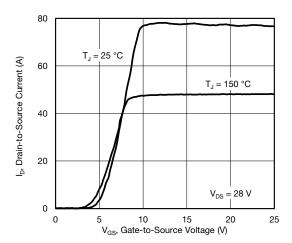


Fig. 3 - Typical Transfer Characteristics

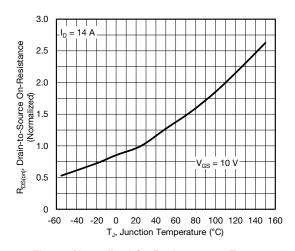


Fig. 4 - Normalized On-Resistance vs. Temperature

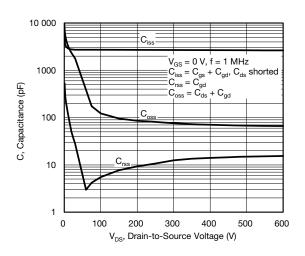


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

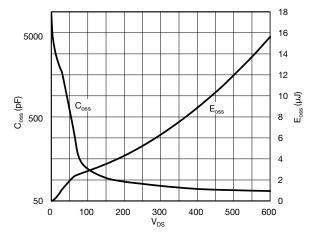


Fig. 6 - Coss and Eoss vs. VDS



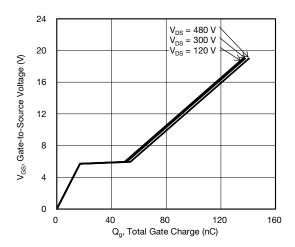


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

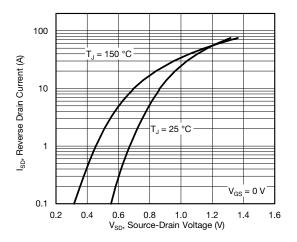


Fig. 8 - Typical Source-Drain Diode Forward Voltage

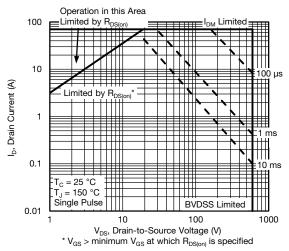


Fig. 9 - Maximum Safe Operating Area

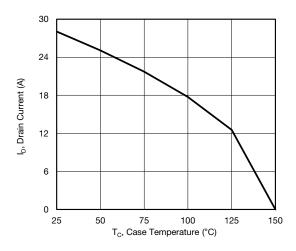


Fig. 10 - Maximum Drain Current vs. Case Temperature

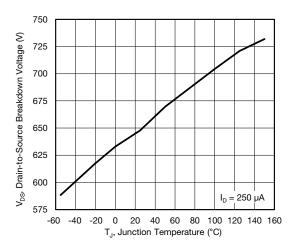


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature



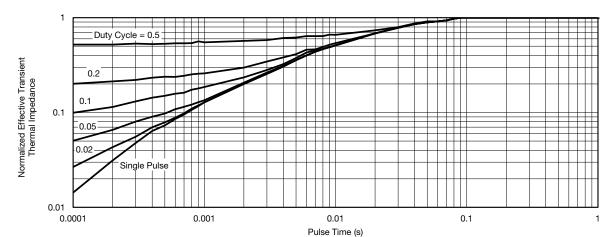


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

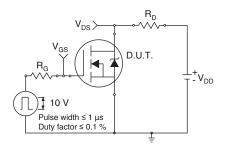


Fig. 13 - Switching Time Test Circuit

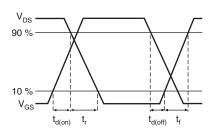


Fig. 14 - Switching Time Waveforms

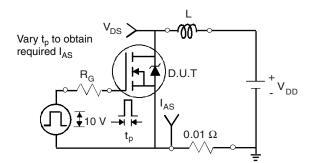


Fig. 15 - Unclamped Inductive Test Circuit

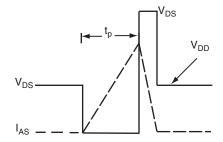


Fig. 16 - Unclamped Inductive Waveforms

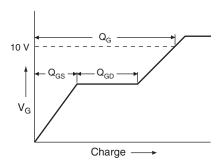


Fig. 17 - Basic Gate Charge Waveform

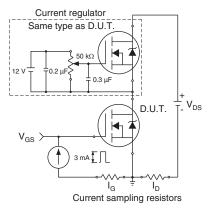
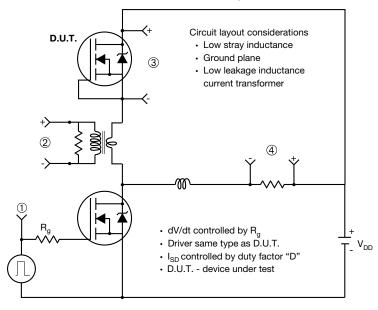


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



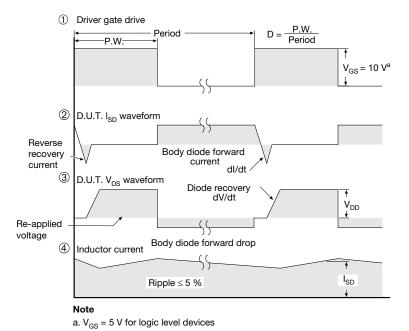


Fig. 19 - For N-Channel

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